Infineon Technologies - MB90F922NCSPMC-GE1 Datasheet

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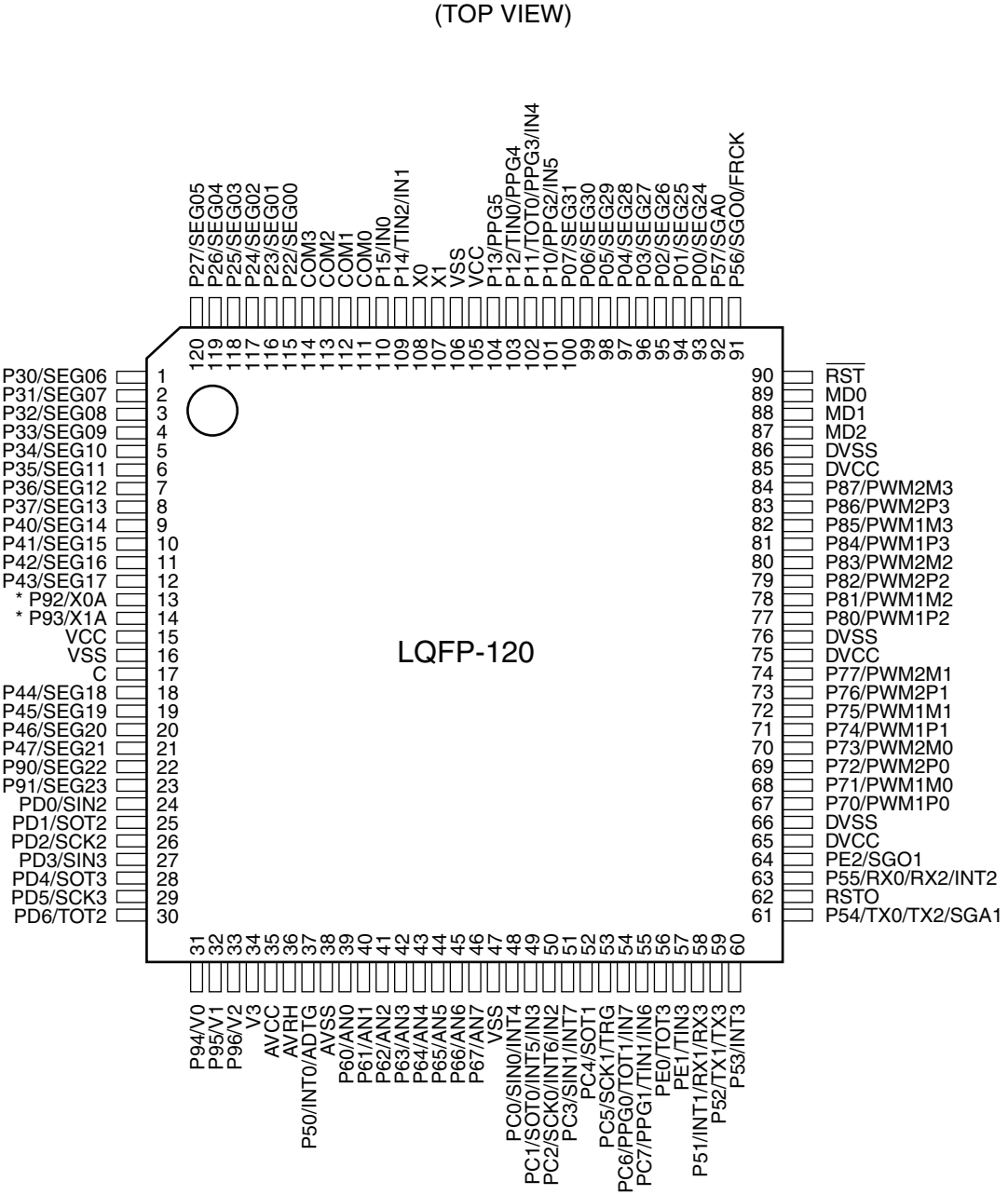
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, LINbus, UART/USART
Peripherals	LCD, LVD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90f922ncspmc-ge1

■ PIN ASSIGNMENT



(FPT-120P-M21)

* : MB90V920-101, MB90F922NCS,MB90F923NCS,MB90F924NCS,MB90922NCS : P92, P93
MB90V920-102, MB90F922NC,MB90F923NC,MB90F924NC : X0A, X1A

Pin no.	Pin name	I/O circuit type*1	Function
104	P13	I	General-purpose I/O port
	PPG5		16-bit PPG ch.5 output pin
109	P14	I	General-purpose I/O port
	TIN2		16-bit reload timer ch.2 TIN input pin
	IN1		Input capture ch.1 trigger input pin
110	P15	I	General-purpose I/O port
	IN0		Input capture ch.0 trigger input pin
111	COM0	P	LCD controller/driver common output pin
112	COM1	P	LCD controller/driver common output pin
113	COM2	P	LCD controller/driver common output pin
114	COM3	P	LCD controller/driver common output pin
115	P22	F	General-purpose I/O port
	SEG00		LCD controller/driver segment output pin
116	P23	F	General-purpose I/O port
	SEG01		LCD controller/driver segment output pin
117	P24	F	General-purpose I/O port
	SEG02		LCD controller/driver segment output pin
118	P25	F	General-purpose I/O port
	SEG03		LCD controller/driver segment output pin
119	P26	F	General-purpose I/O port
	SEG04		LCD controller/driver segment output pin
120	P27	F	General-purpose I/O port
	SEG05		LCD controller/driver segment output pin
1	P30	F	General-purpose I/O port
	SEG06		LCD controller/driver segment output pin
2	P31	F	General-purpose I/O port
	SEG07		LCD controller/driver segment output pin
3	P32	F	General-purpose I/O port
	SEG08		LCD controller/driver segment output pin
4	P33	F	General-purpose I/O port
	SEG09		LCD controller/driver segment output pin
5	P34	F	General-purpose I/O port
	SEG10		LCD controller/driver segment output pin
6	P35	F	General-purpose I/O port
	SEG11		LCD controller/driver segment output pin

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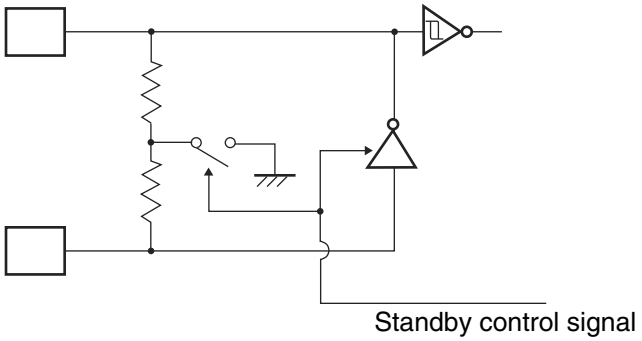
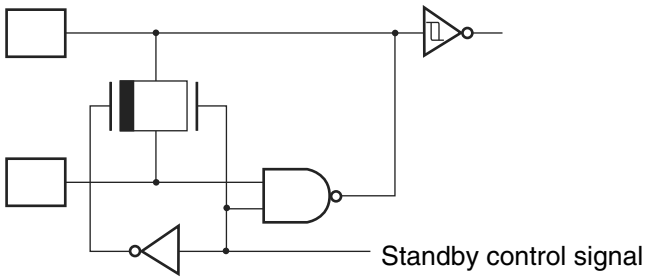
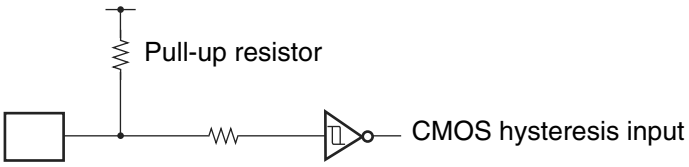
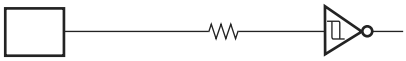
■ I/O CIRCUIT TYPE

Type	Circuit	Remarks
A		Oscillation circuit High-speed oscillation feedback resistance : approx. 1 MΩ (Flash memory product/MASK ROM product/Evaluation product)
B		Oscillation circuit Low-speed oscillation feedback resistance : approx. 10 MΩ
C		Input-only pin (with pull-up resistance) • Attached pull-up resistor : approx. 50 kΩ • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC})
D		Input-only pin • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) Note: The MD2 pin of the Flash memory products uses this circuit type.

(Continued)

■ HANDLING DEVICES

• Strictly observe maximum rated voltages (preventing latch-up)

In CMOS IC devices, a condition known as latch-up may occur if voltages higher than V_{CC} or lower than V_{SS} are applied to input or output pins other than medium or high withstand voltage pins, or if the voltage applied between VCC and VSS pins exceeds the rated voltage level. If a latch-up occurs, the power supply current may increase dramatically and may destroy semiconductor elements. When using semiconductor devices, always take sufficient care to avoid exceeding maximum ratings.

When the analog system power supply is switched on or off, be careful not to apply the analog power supply (AV_{CC}, AVRH), the analog input voltages and the power supply voltage for the high current output buffer pins (DV_{CC}) in excess of the digital power supply voltage (V_{CC}).

Once the digital power supply voltage (V_{CC}) has been disconnected, the analog power supply (AV_{CC}, AVRH) and the power supply voltage for the high current output buffer pins (DV_{CC}) may be turned on in any sequence.

• Supply voltage stabilization

Rapid fluctuations in the power supply voltage can cause malfunctions even if the Vcc power supply voltage remains within the warranted operating range. It is recommended that the power supply be stabilized such that ripple fluctuations (P-P value) at commercial frequencies (50 Hz/60 Hz) be limited to within 10% of the standard V_{CC} value, and that transient fluctuations due to power supply switching, etc. be limited to a rate of 0.1 V/ms or less.

• Precautions when turning the power on

In order to prevent the built-in step-down circuits from malfunctioning, the time taken for the voltage to rise (0.2 V to 2.7 V) during power-on should be less than 50 μs.

• Handling unused pins

If unused input pins are left open, they may cause malfunctions or latch-up which may lead to permanent damage to the semiconductor. Unused input pins should therefore be pulled up or pulled down through a resistor of at least 2 kΩ.

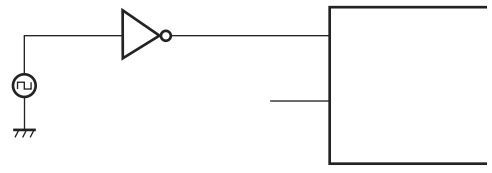
Unused input/output pins may be set to the output state and left open, or set to the input state and connected to a pull-up or pull-down resistance of 2 kΩ or more.

• Handling A/D converter power supply pins

Even if the A/D converter is not used, the power supply pins should be connected such as $AV_{CC} = V_{CC}$, and $AV_{SS} = AVRH = V_{SS}$.

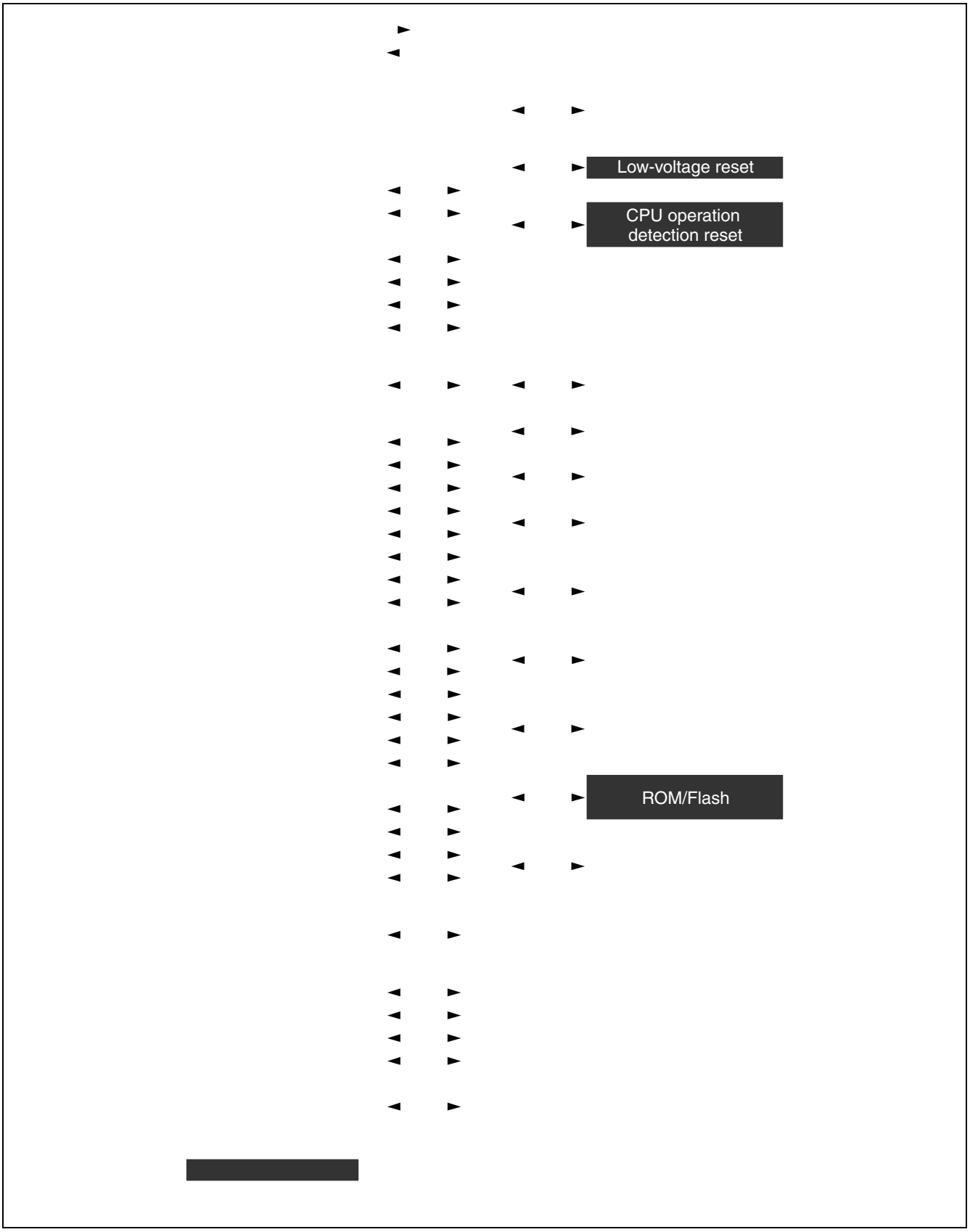
• Notes on using an external clock

Even when an external clock is used, an oscillation stabilization wait time is required following power-on reset or release from sub clock mode or stop mode. Furthermore, only the X0A pin should be driven when an external clock is used, with the X1A pin open as shown in the following diagram. Do not use high-speed oscillation pins (X0 and X1) for external clock input.



Sample external clock connection

■ BLOCK DIAGRAM



■ I/O MAP

Address	Register name	Symbol	Read/write	Resource name	Initial value
000000H	Port 0 data register	PDR0	R/W	Port 0	XXXXXXXXB
000001H	Port 1 data register	PDR1	R/W	Port 1	XXXXXXXXB
000002H	Port 2 data register	PDR2	R/W	Port 2	XXXXXXXXB
000003H	Port 3 data register	PDR3	R/W	Port 3	XXXXXXXXB
000004H	Port 4 data register	PDR4	R/W	Port 4	XXXXXXXXB
000005H	Port 5 data register	PDR5	R/W	Port 5	XXXXXXXXB
000006H	Port 6 data register	PDR6	R/W	Port 6	XXXXXXXXB
000007H	Port 7 data register	PDR7	R/W	Port 7	XXXXXXXXB
000008H	Port 8 data register	PDR8	R/W	Port 8	XXXXXXXXB
000009H	Port 9 data register	PDR9	R/W	Port 9	XXXXXXXXB
00000AH, 00000BH	(Disabled)				
00000CH	Port C data register	PDRC	R/W	Port C	XXXXXXXXB
00000DH	Port D data register	PDRD	R/W	Port D	XXXXXXXXB
00000EH	Port E data register	PDRE	R/W	Port E	XXXXXXXXB
00000FH	(Disabled)				
000010H	Port 0 direction register	DDR0	R/W	Port 0	00000000B
000011H	Port 1 direction register	DDR1	R/W	Port 1	XX000000B
000012H	Port 2 direction register	DDR2	R/W	Port 2	000000XXB
000013H	Port 3 direction register	DDR3	R/W	Port 3	00000000B
000014H	Port 4 direction register	DDR4	R/W	Port 4	00000000B
000015H	Port 5 direction register	DDR5	R/W	Port 5	00000000B
000016H	Port 6 direction register	DDR6	R/W	Port 6	00000000B
000017H	Port 7 direction register	DDR7	R/W	Port 7	00000000B
000018H	Port 8 direction register	DDR8	R/W	Port 8	00000000B
000019H	Port 9 direction register	DDR9	R/W	Port 9	X0000000B
00001AH	Analog input enable	ADER6	R/W	Port 6, A/D	11111111B
00001BH	(Disabled)				
00001CH	Port C direction register	DDRC	R/W	Port C	00000000B
00001DH	Port D direction register	DDRD	R/W	Port D	X0000000B
00001EH	Port E direction register	DDRE	R/W	Port E	XXXXX000B
00001FH	(Disabled)				
000020H	Lower A/D control status register	ADCS0	R/W	A/D converter	000XXXX0B
000021H	Higher A/D control status register	ADCS1	R/W		0000000XB
000022H	Lower A/D control status register	ADCR0	R		00000000B
000023H	Higher A/D data register	ADCR1	R		XXXXXX00B

(Continued)

Address	Register name	Symbol	Read/write	Resource name	Initial value
000083H	(Disabled)				
000084H	PWM control register 2	PWC2	R/W	Stepping motor controller 2	000000X0B
000085H	(Disabled)				
000086H	PWM control register 3	PWC3	R/W	Stepping motor controller 3	000000X0B
000087H	(Disabled)				
000088H	LCD output control register 3	LOCR3	R/W	LCDC	XXXXX111B
000089H	(Disabled)				
00008AH	A/D setting register 0	ADSR0	R/W	A/D converter	00000000B
00008BH	A/D setting register 1	ADSR1	R/W		00000000B
00008CH	Port input level select 0	PIL0	R/W	Port input level select	00000000B
00008DH	Port input level select 1	PIL1	R/W		XXXX0000B
00008EH	Port input level select 2	PIL2	R/W		XXXX0000B
00008FH to 00009DH	(Disabled)				
00009EH	Program address detection control register	PACSR	R/W	Address match detection	XXXX0X0XB
00009FH	Delayed Interrupt/Release Register	DIRR	R/W	Delay interrupt	XXXXXXX0B
0000A0H	Power saving mode control register	LPMCR	R/W	Power saving control circuit	00011000B
0000A1H	Clock select register	CKSCR	R/W, R		11111100B
0000A2H to 0000A7H	(Disabled)				
0000A8H	Watchdog timer control register	WDTC	R, W	Watchdog timer	XXXXX111B
0000A9H	Time-base timer control register	TBTC	R/W, W	Time-base timer	1XX00100B
0000AAH	Watch timer control register	WTC	R/W, W, R	Watch timer (sub clock)	10001000B
0000ABH to 0000ADH	(Disabled)				
0000AEH	Flash memory control status register	FMCS	R/W	Flash interface	000X0000B
0000AFH	(Disabled)				

(Continued)

Address	Register name	Symbol	Read/write	Resource name	Initial value
0000D4H	Lower timer control status register 2	TMCSR2L	R/W	16-bit reload timer 2	00000000B
0000D5H	Higher timer control status register 2	TMCSR2H	R/W		XXX10000B
0000D6H	Lower timer control status register 3	TMCSR3L	R/W	16-bit reload timer 3	00000000B
0000D7H	Higher timer control status register 3	TMCSR3H	R/W		XXX10000B
0000D8H	Lower sound control register 1	SGCRL1	R/W	Sound generator 1	00000000B
0000D9H	Higher sound control register 1	SGCRH1	R/W		0XXXX100B
0000DAH	Lower PPG3 control status register	PCNTL3	R/W	16-bit PPG3	00000000B
0000DBH	Higher PPG3 control status register	PCNTH3	R/W		00000001B
0000DCH	Lower PPG4 control status register	PCNTL4	R/W	16-bit PPG4	00000000B
0000DDH	Higher PPG4 control status register	PCNTH4	R/W		00000001B
0000DEH	Lower PPG5 control status register	PCNTL5	R/W	16-bit PPG5	00000000B
0000DFH	Higher PPG5 control status register	PCNTH5	R/W		00000001B
0000E0H	Serial mode register 2	SMR2	R/W, W	UART (LIN/SCI) 2	00000000B
0000E1H	Serial control register 2	SCR2	R/W, W		00000000B
0000E2H	Reception/transmission data register 2	RDR2/ TDR2	R/W		00000000B
0000E3H	Serial status register 2	SSR2	R/W, R		00001000B
0000E4H	Extended communication control register 2	ECCR2	R/W, R		000000XXB
0000E5H	Extended status control register 2	ESCR2	R/W		00000100B
0000E6H	Baud rate generator register 20	BGR20	R/W		00000000B
0000E7H	Baud rate generator register 21	BGR21	R/W, R		00000000B
0000E8H	Serial mode register 3	SMR3	R/W, W	UART (LIN/SCI) 3	00000000B
0000E9H	Serial control register 3	SCR3	R/W, W		00000000B
0000EAH	Reception/transmission data register 3	RDR3/ TDR3	R/W		00000000B
0000EBH	Serial status register 3	SSR3	R/W, R		00001000B
0000ECH	Extended communication control register 3	ECCR3	R/W, R		000000XXB
0000EDH	Extended status control register 3	ESCR3	R/W		00000100B
0000EEH	Baud rate generator register 30	BGR30	R/W		00000000B
0000EFH	Baud rate generator register 31	BGR31	R/W, R		00000000B
001FF0H	Program address detection register 0	PADR0	R/W	Address match detection	XXXXXXXXB
001FF1H	Program address detection register 1	PADR0	R/W		XXXXXXXXB
001FF2H	Program address detection register 2	PADR0	R/W		XXXXXXXXB
001FF3H	Program address detection register 3	PADR1	R/W		XXXXXXXXB
001FF4H	Program address detection register 4	PADR1	R/W		XXXXXXXXB
001FF5H	Program address detection register 5	PADR1	R/W		XXXXXXXXB

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■ CAN CONTROLLERS

The CAN controller has the following features :

- Conforms to CAN Specification Version 2.0 Part A and B
  - Supports transmission/reception in standard frame and extended frame formats
- Supports transmission of data frames by receiving remote frames
- 16 transmission/reception message buffers
  - 29-bit ID and 8-byte data
  - Multi-level message buffer configuration
- Provides full-bit comparison, full-bit mask, acceptance register 0/acceptance register 1 for each message buffer as ID acceptance mask
  - 2 acceptance mask registers in either standard frame format or extended frame formats
- Bit rate programmable from 10 kbps to 2 Mbps (when input clock is at 16 MHz)

List of Control Registers(1)

Address				Register	Abbreviation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003C00H	003D00H	003E00H	003F00H	Control status register	CSR	R/W, R	00---000B 0----0-1B
003C01H	003D01H	003E01H	003F01H				
003C02H	003D02H	003E02H	003F02H	Last event indicator register	LEIR	R/W	--------B 000-0000B
003C03H	003D03H	003E03H	003F03H				
003C04H	003D04H	003E04H	003F04H	RX/TX error counter	RTEC	R	00000000B 00000000B
003C05H	003D05H	003E05H	003F05H				
003C06H	003D06H	003E06H	003F06H	Bit timing register	BTR	R/W	-1111111B 11111111B
003C07H	003D07H	003E07H	003F07H				

List of Message Buffers (ID Registers)

Address				Register	Abbre-viation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003A00H to 003A1FH	003B00H to 003B1FH	003700H to 00371FH	003800H to 00381FH	General-purpose RAM	—	R/W	XXXXXXXXB to XXXXXXXXB
003A20H	003B20H	003720H	003820H	ID register 0	IDR0	R/W	XXXXXXXXB XXXXXXXXB
003A21H	003B21H	003721H	003821H				
003A22H	003B22H	003722H	003822H				XXXXX---B XXXXXXXXB
003A23H	003B23H	003723H	003823H				
003A24H	003B24H	003724H	003824H	ID register 1	IDR1	R/W	XXXXXXXXB XXXXXXXXB
003A25H	003B25H	003725H	003825H				
003A26H	003B26H	003726H	003826H				XXXXX---B XXXXXXXXB
003A27H	003B27H	003727H	003827H				
003A28H	003B28H	003728H	003828H	ID register 2	IDR2	R/W	XXXXXXXXB XXXXXXXXB
003A29H	003B29H	003729H	003829H				
003A2AH	003B2AH	00372AH	00382AH				XXXXX---B XXXXXXXXB
003A2BH	003B2BH	00372BH	00382BH				
003A2CH	003B2CH	00372CH	00382CH	ID register 3	IDR3	R/W	XXXXXXXXB XXXXXXXXB
003A2DH	003B2DH	00372DH	00382DH				
003A2EH	003B2EH	00372EH	00382EH				XXXXX---B XXXXXXXXB
003A2FH	003B2FH	00372FH	00382FH				
003A30H	003B30H	003730H	003830H	ID register 4	IDR4	R/W	XXXXXXXXB XXXXXXXXB
003A31H	003B31H	003731H	003831H				
003A32H	003B32H	003732H	003832H				XXXXX---B XXXXXXXXB
003A33H	003B33H	003733H	003833H				
003A34H	003B34H	003734H	003834H	ID register 5	IDR5	R/W	XXXXXXXXB XXXXXXXXB
003A35H	003B35H	003735H	003835H				
003A36H	003B36H	003736H	003836H				XXXXX---B XXXXXXXXB
003A37H	003B37H	003737H	003837H				
003A38H	003B38H	003738H	003838H	ID register 6	IDR6	R/W	XXXXXXXXB XXXXXXXXB
003A39H	003B39H	003739H	003839H				
003A3AH	003B3AH	00373AH	00383AH				XXXXX---B XXXXXXXXB
003A3BH	003B3BH	00373BH	00383BH				
003A3CH	003B3CH	00373CH	00383CH	ID register 7	IDR7	R/W	XXXXXXXXB XXXXXXXXB
003A3DH	003B3DH	00373DH	00383DH				
003A3EH	003B3EH	00373EH	00383EH				XXXXX---B XXXXXXXXB
003A3FH	003B3FH	00373FH	00383FH				

(Continued)

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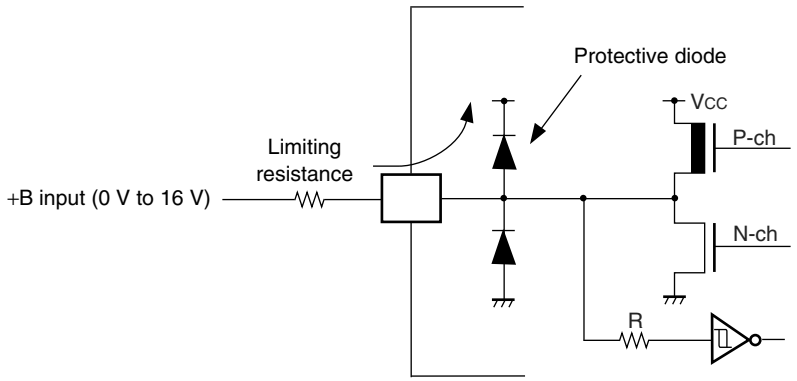
*5 : Average output current is defined as the average value of the current flowing through any one of the corresponding pins within a period of 100 ms. The “average value” can be calculated by multiplying the “operating current” by the “operating factor”.

*6 : Average total output current is defined as the average value of the current flowing through all of the corresponding pins within a period of 100 ms. The “average value” can be calculated by multiplying the “operating current” by the “ operating factor”.

*7 :
- Applicable to pins: P10 to P15,P50 to P57,P60 to P67,P70 to P77,P80 to P87,PC0 to PC7,PD0 to PD6, PE0 to PE2
- Use within recommended operating conditions.
- Use at DC voltage (current) .
- The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.
- The value of the limiting resistance should be set so that when the +B signal is applied, the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0 V) , the microcontroller may partially malfunction on power supplied through the +B signal pin.
- Note that if the +B input is applied during power-on, the power supply voltage may reach a level such that the power-on reset does not function due to the power supplied from the +B signal.
- Care must be taken not to leave +B input pins open.
- Note that analog system input/output pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signal inputs.
- Sample recommended circuit :

• Input/output equivalent circuit



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

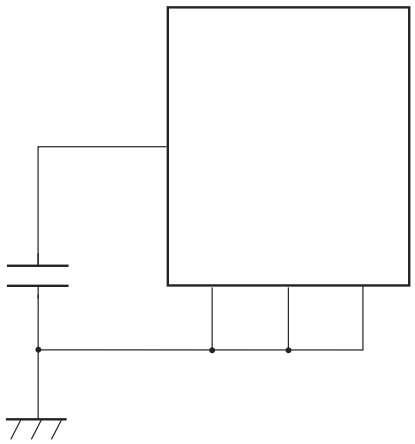
2. Recommended Operating Conditions

(V_{SS} = DV_{SS} = AV_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
Power supply voltage	V_{CC} AV_{CC} DV_{CC}	4.0	5.5	V	The low voltage detection reset operates when the power supply voltage reaches 4.2 V ± 0.2 V.
		4.4	5.5	V	Maintain stop operation status The low voltage detection reset operates when the power supply voltage reaches 4.2 V ± 0.2 V.
Smoothing capacitor*	C_S	0.1	1.0	µF	Use a ceramic capacitor or other capacitor of equivalent frequency characteristics. Use a capacitor with a capacitance greater than this capacitor as the bypass capacitor for the V_{CC} pin.
Operating temperature	T_A	− 40	+ 105	°C	

* : Refer to the following diagram for details on the connection of the smoothing capacitor C_S.

• C pin connection diagram



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

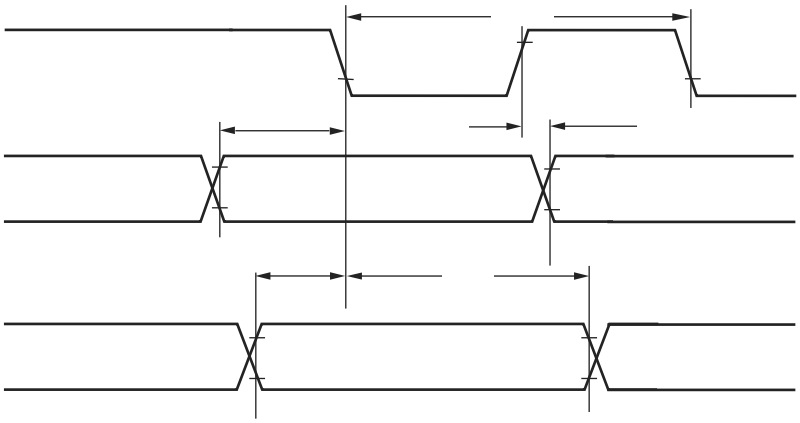
No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

• **Bit setting: ESCR0/1/2/3:SCES=0, ECCR0/1/2/3:SCDE=1**

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCK0 to SCK3, SOT0 to SOT3		– 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSLI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↓ → valid SIN hold time	t_{SLIXI}			0	—	ns
SOT → SCK ↓ delay time	t_{SOVLI}	SCK0 to SCK3, SOT0 to SOT3		3 t_{CP} – 70	—	ns

Notes : • Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
• C_L is the load capacitance connected to the pin during testing.
• t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

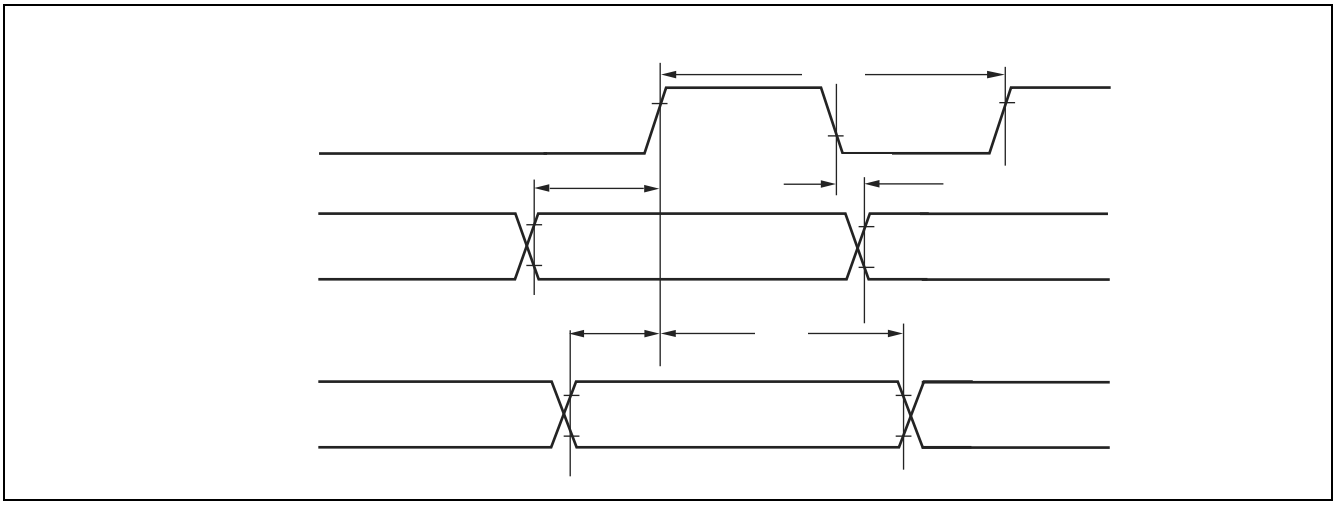


• **Bit setting: ESCR0/1/2/3:SCES=1, ECCR0/1/2/3:SCDE=1**

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		– 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXI}			0	—	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCK0 to SCK3, SOT0 to SOT3		3 t_{CP} – 70	—	ns

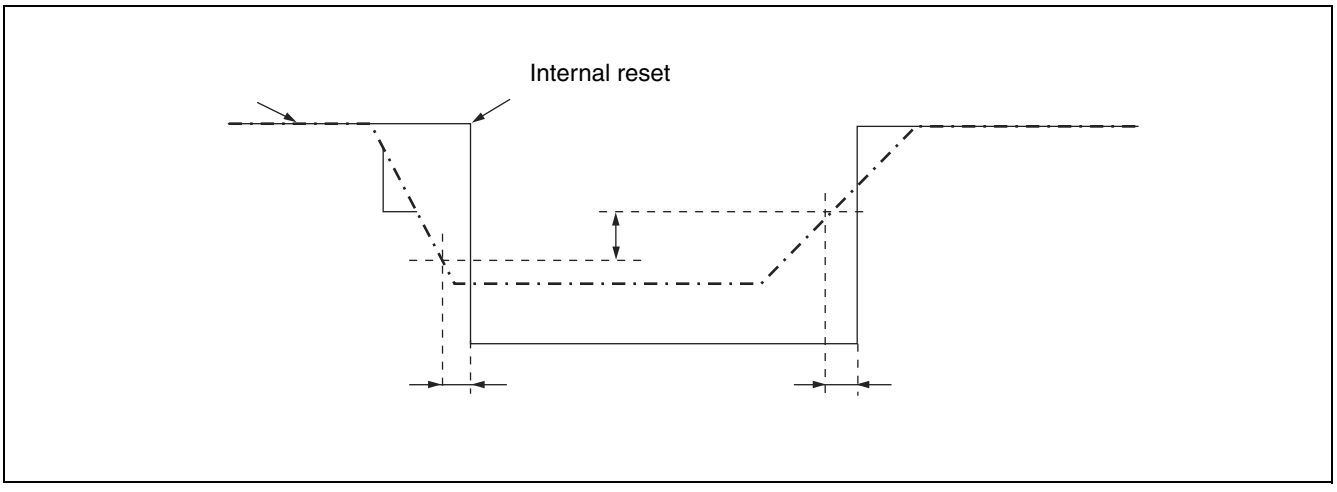
Notes :
- Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
- C_L is the load capacitance connected to the pin during testing.
- t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.



(7) Low voltage detection

(V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Detection voltage	V_{DL}	VCC	—	4.0	4.2	4.4	V	Flash memory product, during voltage drop
				3.7	4.0	4.3	V	Evaluation product, during voltage drop
Hysteresis width	V_{HYS}	VCC	—	190	—	—	mV	Flash memory product, during voltage rise
				0.1	—	—	V	Evaluation product, during voltage rise
Power supply voltage change rate	dV/dt	VCC	—	– 0.1	—	+ 0.1	V/µs	Flash memory product, dV/dt at low voltage reset
				–0.004	—	+ 0.004	V/µs	Flash memory product, dV/dt at standard value of low voltage detection/release voltage
				– 0.1	—	+ 0.02	V/µs	Evaluation product
Detection delay time	td	—	—	—	—	3.2	µs	Flash memory product, when dV/dt ≤ 0.004 V/µs
				—	—	35	µs	Evaluation product



5. A/D Converter

(1) Electrical Characteristics

(V_{CC} = AV_{CC} = AVRH = 4.0 V to 5.5 V, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

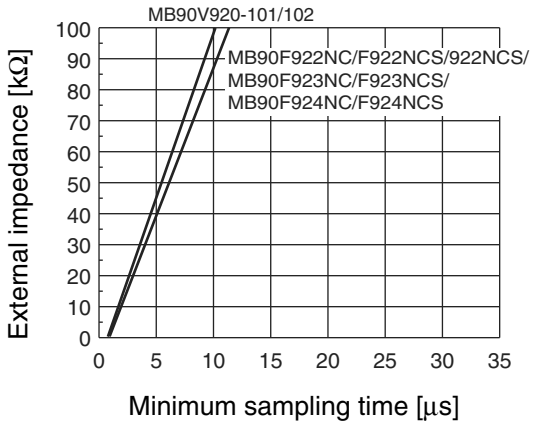
Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	—	—	—	—	10	bit	
Total error	—	—	– 3.0	—	+ 3.0	LSB	
Non-linear error	—	—	– 2.5	—	+ 2.5	LSB	
Differential linear error	—	—	– 1.9	—	+ 1.9	LSB	
Zero transition voltage	V_{OT}	AN0 to AN7	AV_{SS} – 1.5 LSB	AV_{SS} + 0.5 LSB	AV_{SS} + 2.5 LSB	V	1 LSB = (AVRH – AV_{SS}) / 1024
Full scale transition voltage	V_{FST}	AN0 to AN7	AVRH – 3.5 LSB	AVRH – 1.5 LSB	AVRH + 0.5 LSB	V	
Sampling time	t_{SMP}	—	0.4	—	16500	µs	4.5 V ≤ AVcc ≤ 5.5 V
			1.0				4.0 V ≤ AVcc ≤ 4.5 V
Compare time	t_{CMP}	—	0.66	—	—	µs	4.5 V ≤ AVcc ≤ 5.5 V
			2.2				4.0 V ≤ AVcc ≤ 4.5 V
A/D conversion time	t_{CNV}	—	1.44	—	—	µs	*1
Analog port input current	I_{AIN}	AN0 to AN7	– 0.3	—	+ 10	µA	
Analog input voltage	V_{AIN}	AN0 to AN7	0	—	AVRH	V	
Reference voltage	AV+	AVRH	AVss + 2.7	—	AV_{CC}	V	
Power supply current	I_A	AV_{CC}	—	2.3	6.0	mA	
	I_{AH}		—	—	5	µA	*2
Reference voltage supply current	I_R	AVRH	—	520	900	µA	V_{AVRH} = 5.0 V
	I_{RH}		—	—	5	µA	*2
Inter-channel variation	—	AN0 to AN7	—	—	4	LSB	

*1 : The time per channel (4.5 V ≤ AV_{CC} ≤ 5.5 V, and internal operating frequency = 32 MHz) .

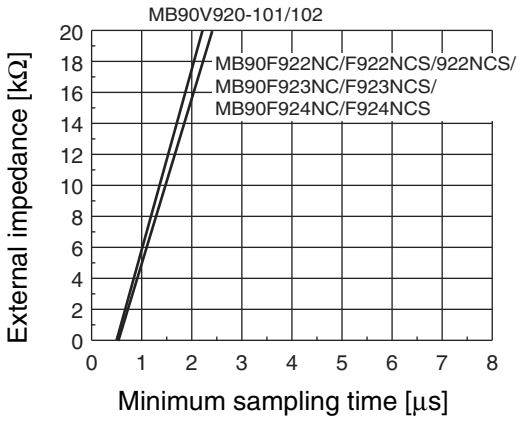
*2 : Defined as supply current (when V_{CC} = AV_{CC} = AVRH = 5.0 V) with A/D converter not operating, and CPU in stop mode.

- The relationship between the external impedance and minimum sampling time
- At 4.5 V ≤ AVcc ≤ 5.5 V

(External impedance = 0 kΩ to 100 kΩ)

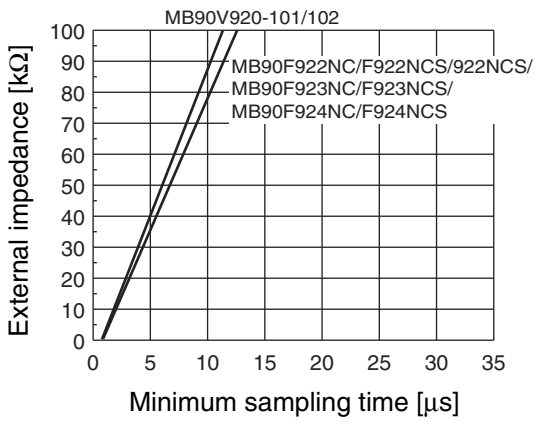


(External impedance = 0 kΩ to 20 kΩ)

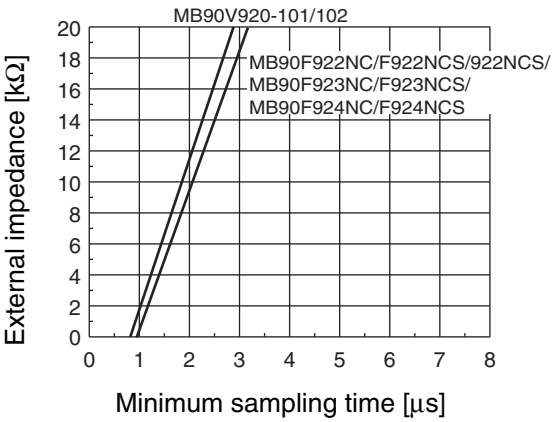


- At 4.0 V ≤ AVcc ≤ 4.5 V

(External impedance = 0 kΩ to 100 kΩ)



(External impedance = 0 kΩ to 20 kΩ)



- About errors
  As |AVRH - AVSS| becomes smaller, the relative errors grow larger.

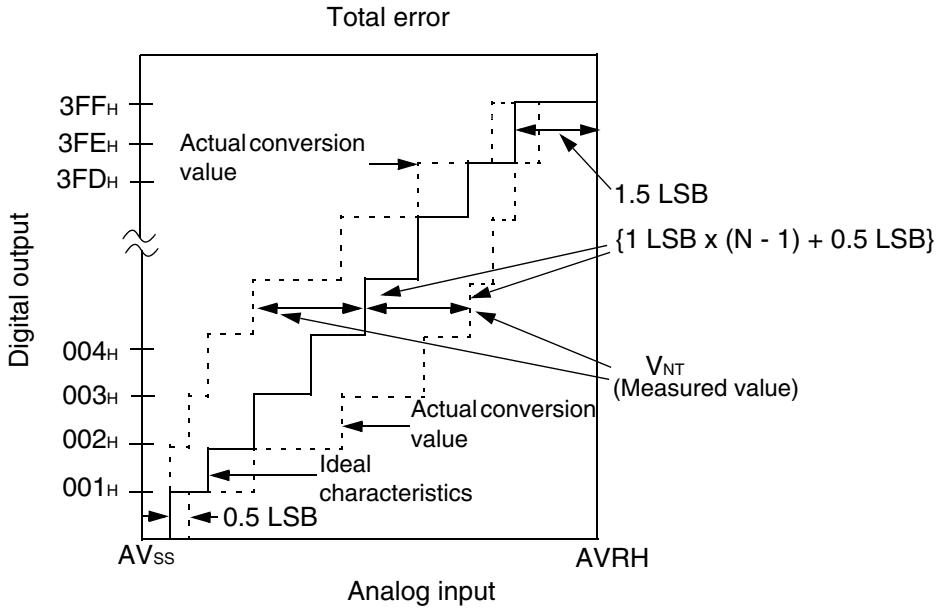
(2) Definition of terms

Resolution : Analog changes that are identifiable by the A/D converter.

Non-Linear error : The deviation of the straight line connecting the zero transition point ("00 0000 0000" ←→ "00 0000 0001") with the full-scale transition point ("11 1111 1110" ←→ "11 1111 1111") from actual conversion characteristics.

Differential linear error : The deviation from the ideal value of the input voltage needed to change the output code by 1 LSB.

Total error : The total error is the difference between the actual value and the theoretical value, and includes zero-transition error/full-scale transition error and linear error.



$$\text{Total error for digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + 0.5\ \text{LSB}\}}{1\ \text{LSB}}\ [\text{LSB}]$$

$$1\ \text{LSB (Ideal)} = \frac{\text{AVRH} - \text{AV}_{SS}}{1024}\ [\text{V}]$$

N : A/D converter digital output value

V_{OT} (Ideal) = AVss + 0.5 LSB [V]

V_{FST} (Ideal) = AVRH − 1.5 LSB [V]

V_{NT} : Voltage when the digital output changes from (N - 1) to N

(Continued)

6. Flash Memory Program/Erase Characteristics

Parameter	Conditions	Value			Unit	Remarks
		Min	Typ	Max		
Sector erase time	T_A = + 25 °C V_{CC} = 5.0 V	—	0.9	3.6	s	Excludes pre-programming before erase
Word (16-bit width) programming time		—	23	370	µs	Excludes system-level overhead
Chip programming time	T_A = + 25 °C, V_{CC} = 5.0 V	—	3.4	55	s	
Erase/program cycle	—	10000	—	—	cycle	
Flash memory data retention time	Average T_A = + 85 °C	20	—	—	year	*

* : This value is calculated from the results of evaluating the reliability of the technology (using Arrhenius equation to translate high temperature measurements into normalized value at + 85 °C) .

■ MAJOR CHANGES IN THIS EDITION

Page	Section	Change Results
12	■I/O CIRCUIT TYPE	Corrected the circuit type B.
20	■ HANDLING DEVICES	Added the following items; • Serial communication • Characteristic difference between flash device and MASK ROM device
31	■ I/O MAP	Corrected “Address: 003970$_H$”. Clock supervisor control register → (Disabled)
46	■ ELECTRICAL CHARACTERISTICS 3. DC Characteristics	Added the item for “LCD output impedance”.
68	■ ORDERING INFORMATION	Corrected the part numbers; MB90V920-101 → MB90V920-101CR MB90V920-102 → MB90V920-102CR

The vertical lines marked in the left side of the page show the changes.